

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1-7. (canceled).

8. (currently amended): A sealing material comprising a fluorine-containing elastomer composition comprising a perfluoroelastomer and an inorganic filler, said inorganic filler consisting of a crystalline carbon allotrope having an average primary particle size of at most 0.1  $\mu\text{m}$ ,

said carbon allotrope being selected from the group consisting of diamond, fullerene and carbon nanotube.

9. (previously presented): The sealing material of Claim 8, wherein the crystalline carbon allotrope having an average primary particle size of at most 0.1  $\mu\text{m}$  is diamond.

10. (canceled).

11. (previously presented): The sealing material for a semiconductor manufacturing equipment of Claim 8.

12-15. (canceled).

16. (currently amended): ~~The sealing material of Claim 8~~ A sealing material comprising a fluorine-containing elastomer composition comprising a perfluoroelastomer and an inorganic filler, wherein the sealing material does not contain an inorganic filler other than ~~the a~~ a crystalline carbon allotrope having an average primary particle size of at most 0.1  $\mu\text{m}$ ,

said carbon allotrope being selected from the group consisting of diamond, fullerene and carbon nanotube.

17. (currently amended): A sealing material comprising a perfluoroelastomer composition comprising a perfluoroelastomer and a crystalline carbon allotrope having an average primary particle size of at most 0.1  $\mu\text{m}$ , said sealing material not containing a metal compound inorganic filler,

said carbon allotrope being selected from the group consisting of diamond, fullerene and carbon nanotube.